

## 3D-Micromac presents enabling dicing technology at Semicon West 2017

3D-Micromac AG will present its microDICE™ laser dicing system and further innovative solutions for processing of semiconductors at Semicon West 2017

3D-Micromac, the leading specialist for laser micromachining, will present its high-performance microDICE™ laser dicing system which brings TLS-Dicing™-Technology (Thermal-Laser-Separation) to semiconductor's back-end. The microDICE™ separates wafer into dies with minimal cost per wafer, an outstanding edge quality while increasing the yield and the throughput. Reasoned by the outstanding advantages in terms of cost, throughput und quality microDICE™ is the first choice to separate SiC wafer.



*The microDICE™ laser micromachining system from 3D-Micromac supports volume production of high-power diodes.*

TLS-Dicing™ uses thermal induced stress, to separate brittle material in one pass. The cleaving-process doesn't ablate or melt any material – no particles are generated. TLS-Dicing™ separates back side metal very smooth and without delamination. Furthermore, TLS-Dicing™ reduces dicing costs per wafer significantly.

### About 3D-Micromac AG

Founded in 2002, 3D-Micromac AG is the industry leader in laser micromachining, delivering powerful, user-friendly and leading edge processes with superior production efficiency. We develop processes, machines and turnkey solutions at the highest technical and technological level. 3D-Micromac systems and services have been successfully implemented in various high-tech industries worldwide including photovoltaic, semiconductor, glass and display industries, micro diagnostics, and medical technology. For more information, visit the company's website at <http://www.3d-micromac.com>

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